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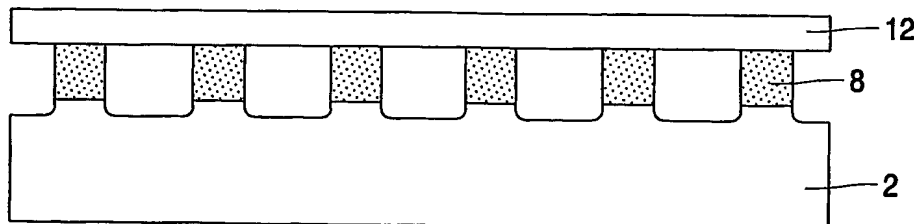
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(54) Title: STRESS-FREE COMPOSITE SUBSTRATE AND METHOD OF MANUFACTURING SUCH A COMPOSITE SUB-  
STRATE



(57) Abstract: A stress free composite substrate is disclosed comprising a carrier (2) composed of a carrier material, a first layer (12) composed of a first material, and an intermediate layer composed of a second material being located between the carrier (2) and the first layer (12), wherein the first material has a dilatation behavior being substantially the same as that of the carrier material, and having a dilatation mismatch with the second material, the intermediate layer (6) having structures (8) of second material for absorbing stress originating from the dilatation mismatch. A method for making such a stress free composite substrate is also disclosed.

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